



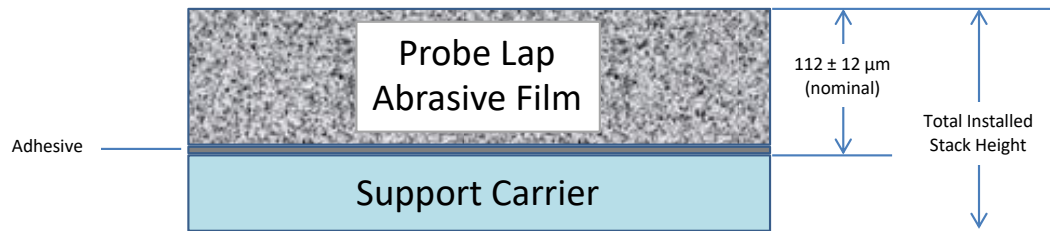
GENERAL

Probe Lap® is used as a direct replacement for on-line lapping film applications. It is built using aluminum-oxide or silicon-carbide abrasive particles. The sheets can be mounted on various substrates and abrasion plates used for on-line and off-line probe cleaning.

Standard Probe Lap® cleaning wafers and cleaning sheets have an operating temperature range -50C to 125C. With additional processing, tempered Probe Lap® high temperature capable cleaning wafers and cleaning sheets can be used at test temperatures up to -50C to 150C. Ultra-Temp Probe Lap sheets and wafers have a maximum operating temperature of 200C.

Material	Material Designation	Material Color	Nominal Abrasive	Operating Temperature				
				-50C	25C	125C	150C	200C
Probe Lap (Standard)	PL-xAH (AIO)	Yellow	0.5 µm	○	○	○		
		Purple	1 µm					
		Green	3 µm					
	PL-xSH (SiC)	Light Gray	1 µm					
		Dark Gray	3 µm					
Probe Lap (High Temp)	PL-xAT (AIO)	Yellow	0.5 µm	○	○	○	○	
		Purple	1 µm					
		Green	3 µm					
	PL-xST (SiC)	Light Gray	1 µm					
		Dark Gray	3 µm					
Probe Lap (Ultra Temp)	PL-xAHT (AIO)	Brown	1 µm	○	○	○	○	○
			3 µm					
	PL-xSHT (SiC)	Gray	1 µm					
			3 µm					

CROSS SECTION



	Cleaning Material Configuration			
	Sheet	200mm Wafer	300mm Wafer	Custom Install
Support Carrier		725 ± 20µm (SEMI Standard)	775 ± 20µm (SEMI Standard)	Contact ITS
Total Installed Stack Height	112 ± 12 µm	837 ± 32µm	887 ± 32 µm	Contact ITS

PROBE LAP®

PCC PD-PL001

